

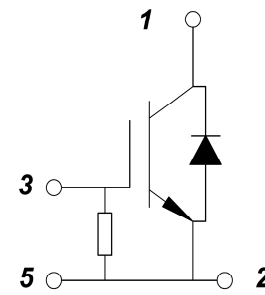
## PRODUCT FEATURES

- IGBT CHIP(Trench+Field Stop technology)
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability
- Fast switching and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Low switching losses
- 10K $\Omega$  Gate Protected Resistance Inside



## APPLICATIONS

- High Power Converters
- Medical applications
- Motion/servo control
- UPS systems/Wind Turbines



### IGBT-inverter

#### ABSOLUTE MAXIMUM RATINGS( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{CES}$	Collector Emitter Voltage	$T_J=25^\circ\text{C}$	1200	V
$V_{GES}$	Gate Emitter Voltage		$\pm 20$	
$I_C$	DC Collector Current	$T_C=25^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	847	A
		$T_C=90^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	600	
$I_{CM}$	Repetitive Peak Collector Current	$t_p=1\text{ms}$	1200	
$P_{tot}$	Power Dissipation Per IGBT	$T_C=25^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	3000	W

### Reverse-Diode

#### ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1200	V
$I_{F(AV)}$	Average Forward Current		400	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1\text{ms}$	800	
$I^2t$		$T_J=125^\circ\text{C}, t=10\text{ms}, V_R=0\text{V}$	39.2	KA <sup>2</sup> S

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# MMG600K120U6TC

## IGBT-inverter

### ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit	
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=12\text{mA}$	5.0	5.8	6.5	V	
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$I_C=600\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.85	2.25		
		$I_C=600\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		2.15			
		$I_C=600\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$		2.2			
$I_{CES}$	Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA	
		$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$			10	mA	
$I_{GES}$	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}, T_J=25^\circ\text{C}$	-2		2	mA	
$R_{gint}$	Integrated Gate Resistor			1		$\Omega$	
$Q_g$	Gate Charge	$V_{CE}=600\text{V}, I_C=600\text{A}, V_{GE}=15\text{V}$		3		$\mu\text{C}$	
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		42		nF	
$C_{res}$	Reverse Transfer Capacitance				2		nF
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=600\text{V}, I_C=600\text{A}$ $R_G=2.7\Omega,$	$T_J=25^\circ\text{C}$		120		ns
			$T_J=150^\circ\text{C}$		140		ns
$t_r$	Rise Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		130		ns
			$T_J=150^\circ\text{C}$		140		ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=600\text{V}, I_C=600\text{A}$ $R_G=2.7\Omega,$	$T_J=25^\circ\text{C}$		700		ns
			$T_J=150^\circ\text{C}$		760		ns
$t_f$	Fall Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		90		ns
			$T_J=150^\circ\text{C}$		160		ns
$E_{on}$	Turn on Energy	$V_{CC}=600\text{V}, I_C=600\text{A}$ $R_G=2.7\Omega,$	$T_J=25^\circ\text{C}$		77		mJ
			$T_J=150^\circ\text{C}$		117		mJ
$E_{off}$	Turn off Energy	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$		56		mJ
			$T_J=150^\circ\text{C}$		76		mJ
$I_{SC}$	Short Circuit Current	$t_{psc}\leq 10\mu\text{s}, V_{GE}=15\text{V}$ $T_J=125^\circ\text{C}, V_{CC}=600\text{V}$		2200		A	
$R_{thJC}$	Junction to Case Thermal Resistance ( Per IGBT )				0.05	K /W	

## Reverse-Diode

### ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.75	2.3	V
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.5		
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$		1.45		
$t_{rr}$	Reverse Recovery Time	$I_F=600\text{A}, V_R=600\text{V}$ $di_F/dt=-4900\text{A}/\mu\text{s}$ $T_J=150^\circ\text{C}$		460		ns
$I_{RRM}$	Max. Reverse Recovery Current			518		A
$Q_{RR}$	Reverse Recovery Charge			130		$\mu\text{C}$
$E_{rec}$	Reverse Recovery Energy			59		mJ
$R_{thJCD}$	Junction to Case Thermal Resistance ( Per Diode )				0.12	K /W

# MMG600K120U6TC

MODULE CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$T_{Jmax}$	Max. Junction Temperature		175	°C
$T_{Jop}$	Operating Temperature		-40~150	
$T_{stg}$	Storage Temperature		-40~125	
$V_{isol}$	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), $t=1$ minute	3000	V
Torque	to heatsink	Recommended (M6)	3~5	Nm
	to terminal	Recommended (M6)	2.5~5	Nm
	to terminal	Recommended (M4)	0.7~1.1	Nm
Weight			330	g

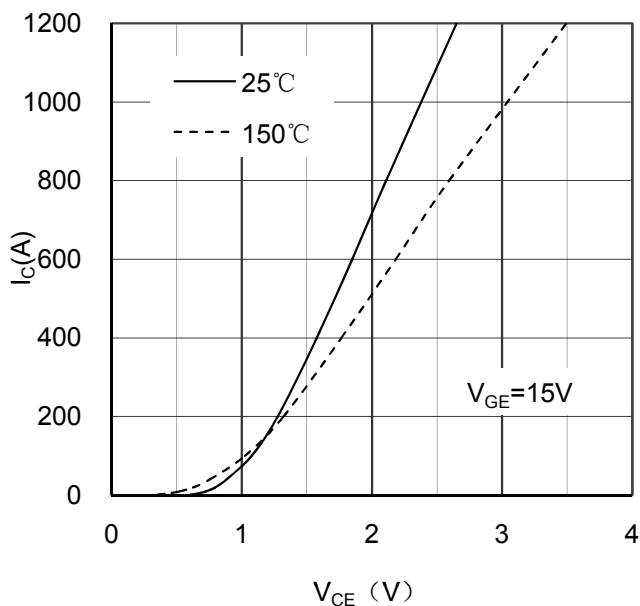


Figure 1. Typical Output Characteristics IGBT-inverter

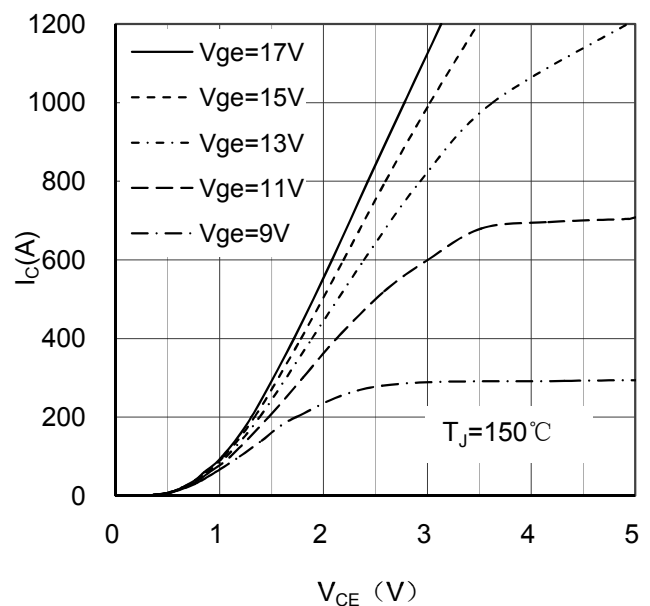


Figure 2. Typical Output Characteristics IGBT-inverter

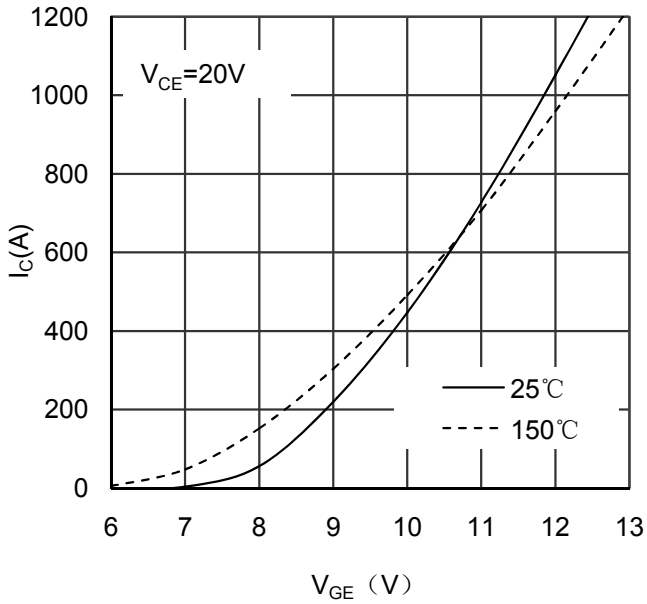


Figure 3. Typical Transfer characteristics IGBT-inverter

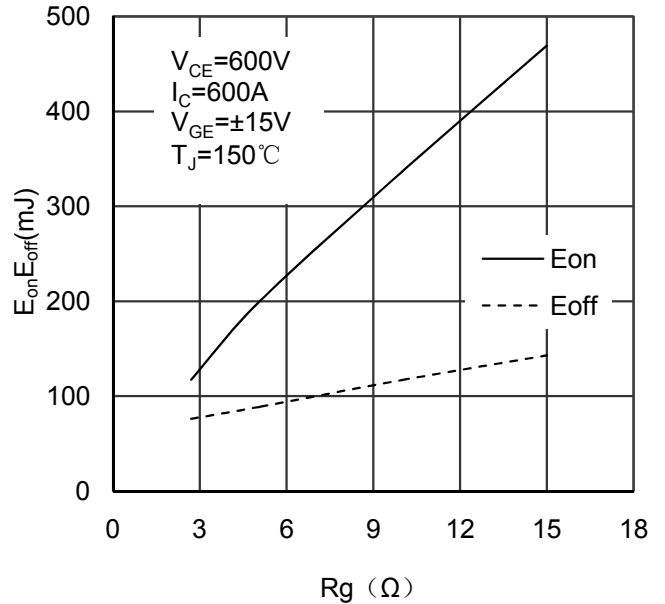


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

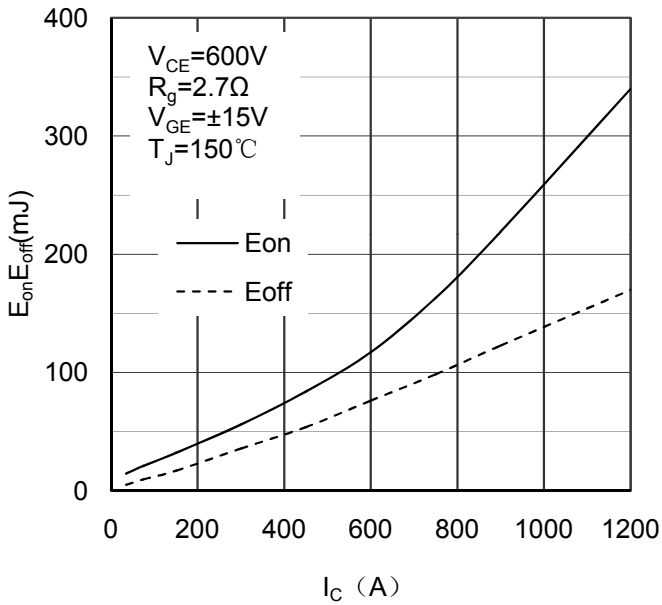


Figure 5. Switching Energy vs Collector Current IGBT-inverter

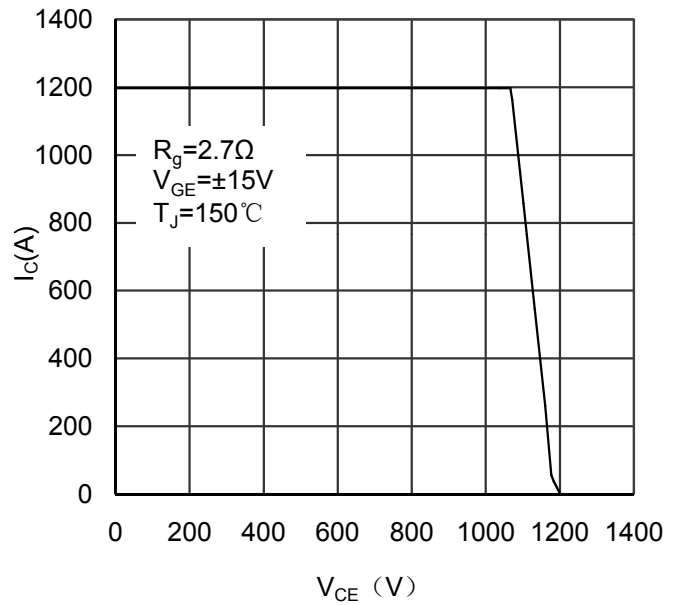


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

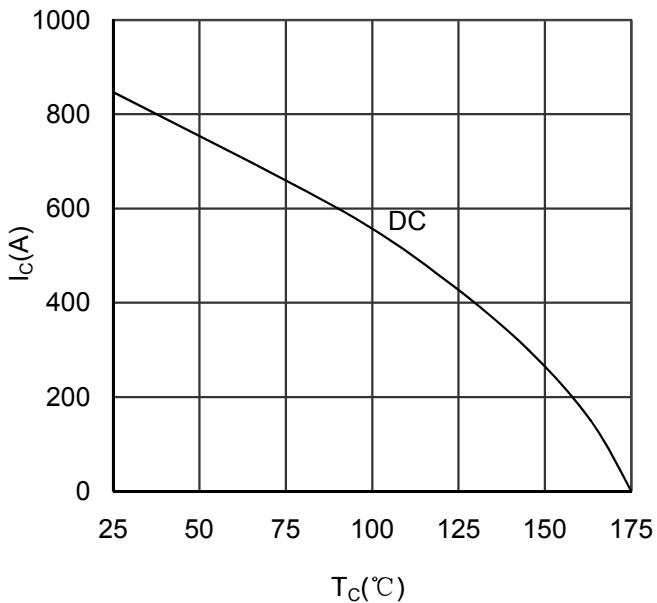


Figure 7. Collector Current vs Case temperature IGBT-inverter

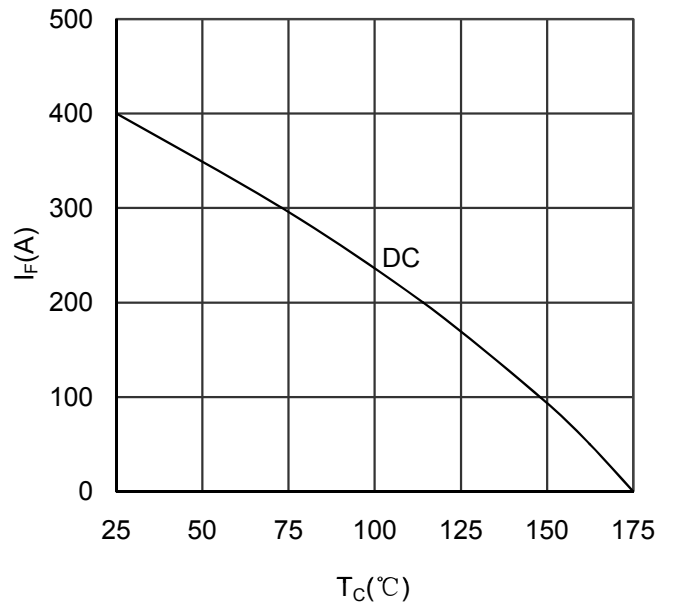


Figure 8. Forward current vs Case temperature Reverse-Diode

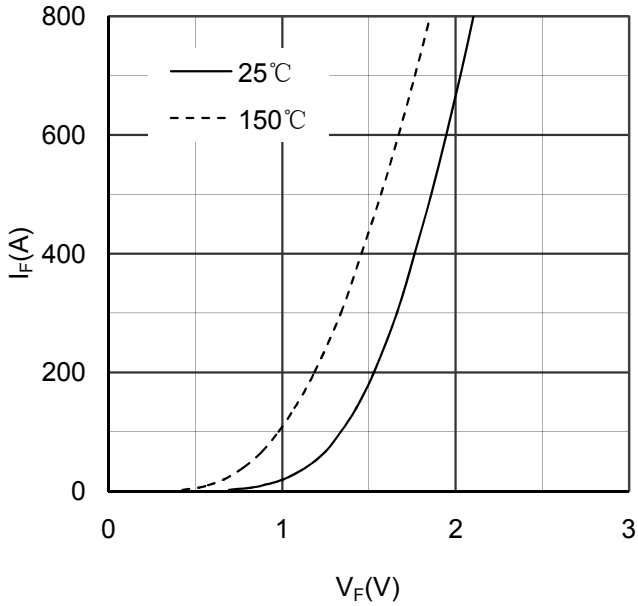


Figure 9. Diode Forward Characteristics Reverse-Diode

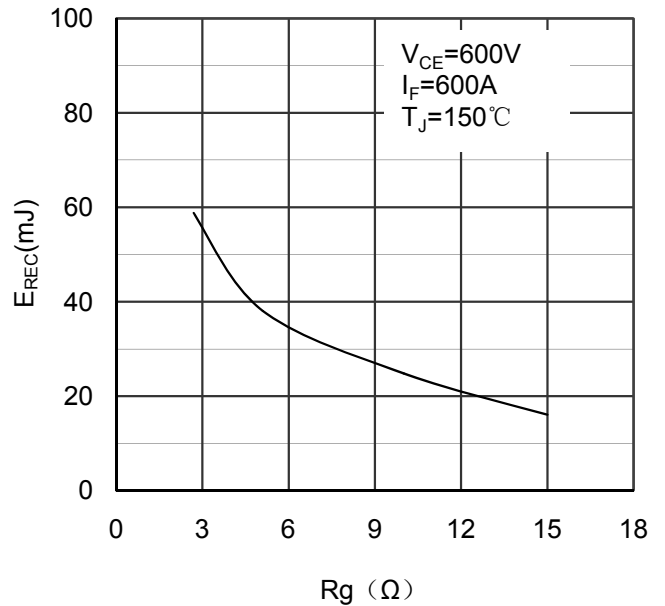


Figure 10. Switching Energy vs Gate Resistor Reverse-Diode

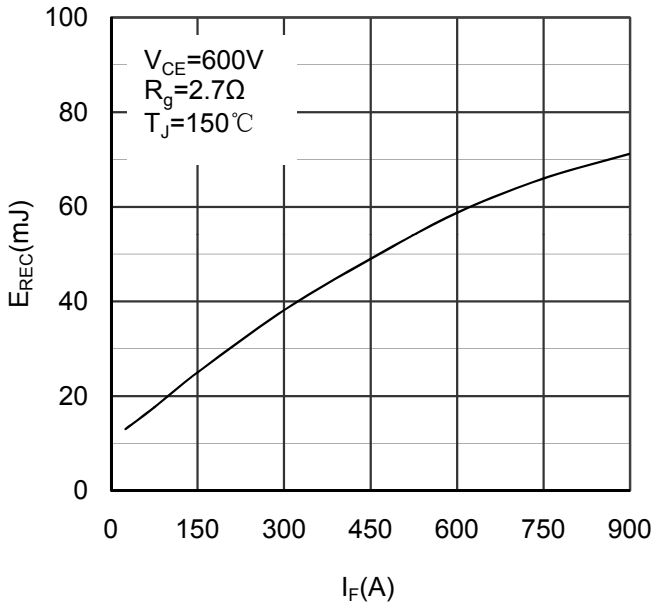


Figure 11. Switching Energy vs Forward Current Reverse-Diode

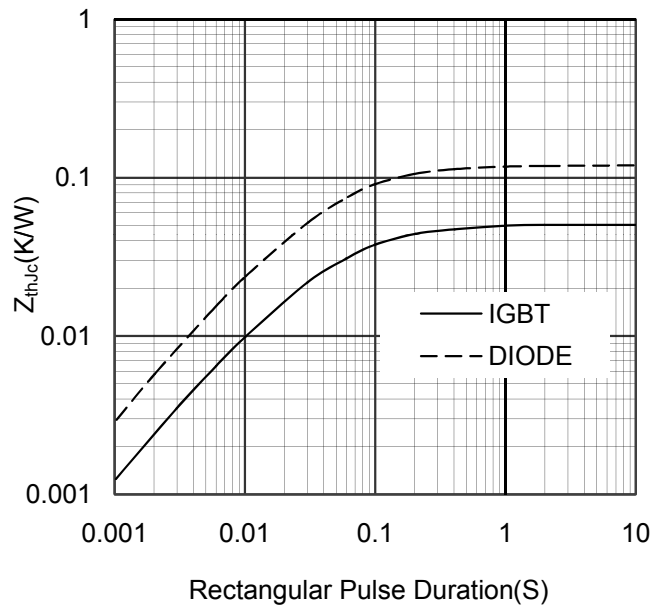


Figure 12. Transient Thermal Impedance of Reverse-Diode and IGBT-inverter

